

AMENDMENTS TO THE CLAIMS

The listing of claims replaces the previous version, and the listing of claims:

LISTING OF CLAIMS

1. (currently amended) A plasma-enhanced processing apparatus, comprising;

a process chamber ~~in which~~ for processing a substrate ~~is processed therein having a wall,~~

a pumping system communicating with said process chamber for exhausting gas in the process chamber,

a gas-introduction system that introduces process gas into said process chamber,

plasma-generation means that generates plasma in said process chamber by applying energy to said process gas,

a substrate holder that holds said substrate in said process chamber, and

an opposite electrode disposed in the process chamber to face said substrate held by said substrate holder, and including a ~~main body, a front board disposed on the main body, and facing the substrate holder,~~ a clamping mechanism ~~that clamps the front board onto the main body so that the front board is pressed onto the main body to have a uniform thermal contact at a side opposite to a side where the plasma is generated~~ plate disposed at a front side of the front board close to the substrate holder so that an area of the front board not covered by the clamping plate is exposed to plasma, and a main body installed on the wall of the process chamber and disposed at a back side of the front board opposite to the front side, said clamping plate contacting a front surface of the front board and pressing the front board toward the main body so that a back surface of the front board is contacted and pressed uniformly onto the main body.

2. (previously presented) A plasma-enhanced processing apparatus as

claimed in claim 1, wherein said opposite electrode includes a cooling mechanism that cools said front board via said main body.

3. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said ~~clamping mechanism includes a~~ clamping plate is in surface contact with said front board to clamp a periphery of the front board.

4. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 3, wherein said front board has a ~~step~~ stepped portion at said periphery that is sandwiched by said main board and said clamping plate, and a front surface of said clamping plate is flush with said front board exposed to the plasma is on a same plane as the front surface of the front board

5. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a protector covering a front surface of said clamping mechanism plate so that said front surface of the clamping plate is not exposed to said plasma.

6. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 5, wherein ~~said clamping mechanism includes a clamping plate in surface contact with~~ said front board has a stepped portion at a periphery sandwiched by the main body and the clamping plate, a back surface of a protector contacting the front surface of the clamping plate, and a front surface of a protector is on a same plane as the front surface of ~~to clamp a periphery of the front board, and said protector is flush with~~ said front board.

7. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, wherein said front board is made of silicon poly-crystal or silicon mono-crystal.

8. (previously presented) A plasma-enhanced processing apparatus as

claimed in claim 3, wherein said clamping plate is screwed on a member except said front board to press said front board onto said main body with screwing torque of 1Nm or more.

9. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, wherein said clamping plate is screwed on a member except said front board to press said front board onto said main body with screwing torque of 1Nm or more.

10. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 6, further comprising a sheet made of carbon inserted between said main body and said front board.

11. (cancelled)

12. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a sheet between the main body and the front board.

13. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 12, wherein said sheet is made of carbon.

14. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 2, wherein said cooling mechanism prevents increase of temperature of the front board in operation.

15. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said opposite electrode further includes an insulation casing disposed around the main body, and ~~said front board has a stepped portion at a periphery thereof, said clamping mechanism engaging the stepped portion to be flush with a surface of the front board and being~~ plate is fixed to the insulation casing at the stepped portion thereof.

16. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 15, ~~wherein said clamping mechanism further includes a clamping plate engaging the stepped portion of the front board, and~~ further comprising a screw for fixing the clamping plate from a lower surface thereof to the insulation casing at the stepped portion thereof.

17. (previously presented) A plasma-enhanced processing apparatus as claimed in claim 16, further comprising an L-shaped protector covering the screw and at least a part of the clamping plate, said L-shaped protector being fixed to the insulation casing at a side thereof.